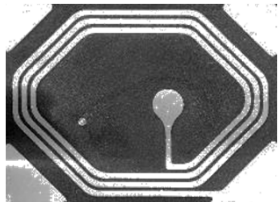
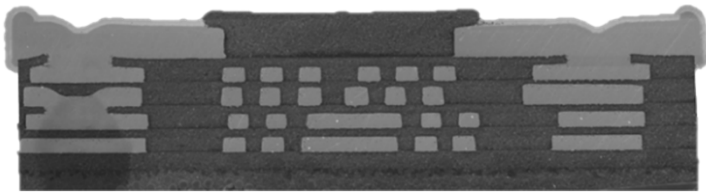
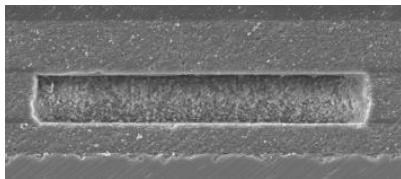


關於 COLP 技術

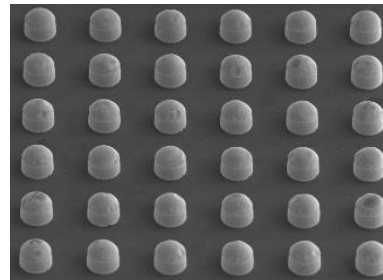
COLP製程 (Copper Organic Laminated Packaging)



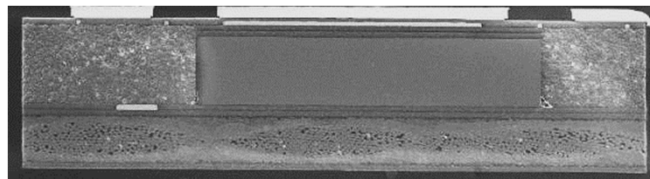
線路重佈層/中介層
RDL/Interposer
5P/5M



氣室結構
Air
Cavity



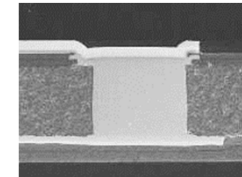
銅柱與錫球
Cu Pillar & Solder Ball



扇入/扇出/晶片箔入
Fan in/Fan out/Chip
Embedded



共模濾波器
Common Mode
Filter



高銅柱
Tall Pillar

COLP 技術 – 產品與服務

- 元件 Components:
 - ◆ 共模濾波器 Common Mode Filters
 - ◆ 高頻濾波器 RF Filters
 - ◆ 六面保護晶片封裝 6 Sides Packaging Diode
- OEM:
 - ◆ 重佈線/銅柱/錫球 RDL/Pillar Bump
 - ◆ 鍍鐵電鍍 NiFe electroplating (for magnetic applications)
 - ◆ 中介層 Interposer
 - ◆ 扇入/扇出封裝 Fan in/Fan out
 - ◆ 內埋晶片 Chip Embedded
 - ◆ 多晶片封裝 Chips Packaging (Single or Multi Die)
- Module:
 - ◆ 高頻前端模組 Front end module
 - ◆ 高頻天線/前端模組 Antenna in Package Module